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The key to monthly features other than articles is as follows: **(A&C)** Advice & Counsel; **(BR)** Book Review; **(CT)** Circuit Topics; **(COM)** Computer Topics; **(ED)** Editorial; **(ES)** Enviroscope; **(FL)** Fine Lines; **(FTT)** Finishers Think Tank; **(FOA)** Focus on the AESF; **(TQM)** Focus on Total Quality Management; **(P&OF)** Pretreatment and Organic Finishing; **(RU)** Regulatory Update; **(SMT)** SMT Topics; **(SVC)** SVC Topics.

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